

ABSTRACT

A method of radiantly marking substrates comprising metals, plastics, ceramic materials, glazes, glass ceramics, and glasses of any desired form, which comprises electrostatically applying to the material to be marked a variable thickness layer of marking material containing energy absorbing components and/or enhancers, then irradiating said layer with a radiant energy source such as a laser or diode based energy source such that the radiation is directed onto said layer, optionally in accordance with the form of the marking to be applied, preferably using a laser or diode based energy source of a wavelength which is sufficiently absorbed by the marking material so as to create a bonding of the marking material to the surface of the workpiece at the irradiated areas.